

# **Irradiation and annealing study of 3D p-type strip detectors**

- **CNM double-sided 3D**
- **Measurements pre-irradiation**
  - **Bulk capacitance**
  - **Leakage current**
  - **Interstrip capacitance**
  - **Interstrip resistance**
- **Post-irradiation and annealing**
- **Future 3D work and other activities**

**Celeste Fleta, Manuel Lozano, Giulio Pellegrini  
(IMB-CNM, Barcelona)**

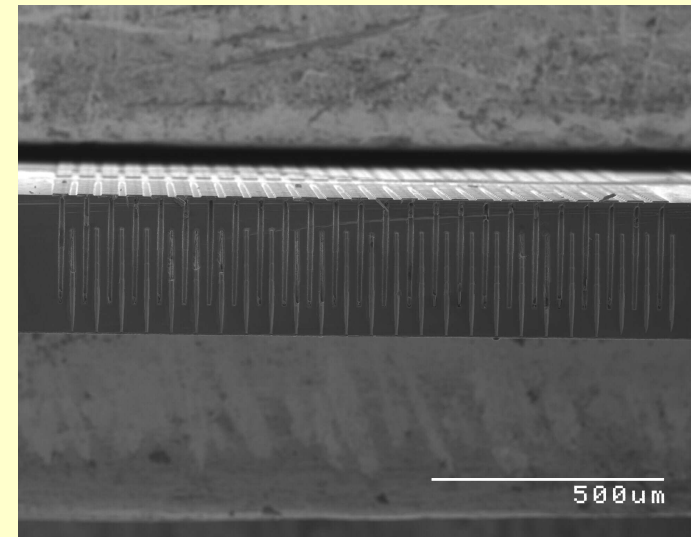
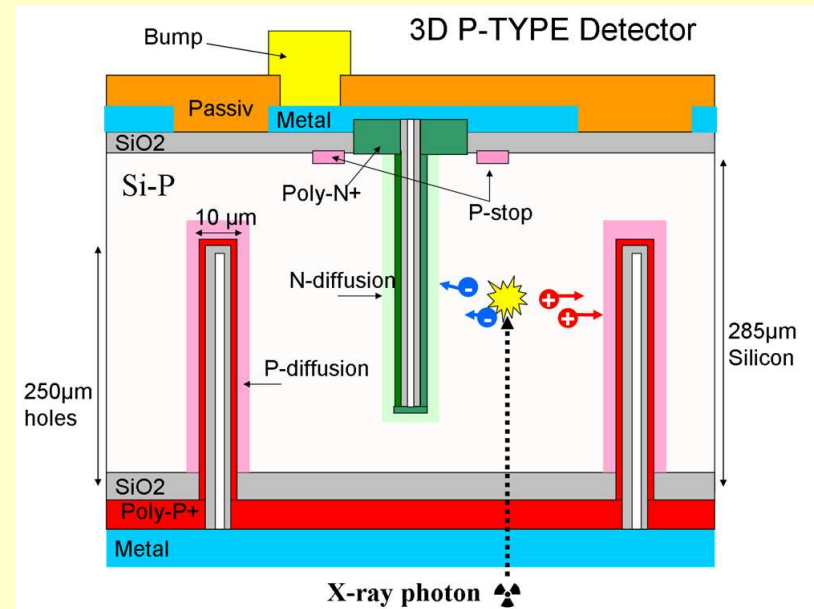
# Double-sided 3D at CNM

- Columns etched from opposite sides of substrate and don't pass through full thickness
- All fabrication done in-house
- ICP is a reliable and repeatable process (many successful runs)

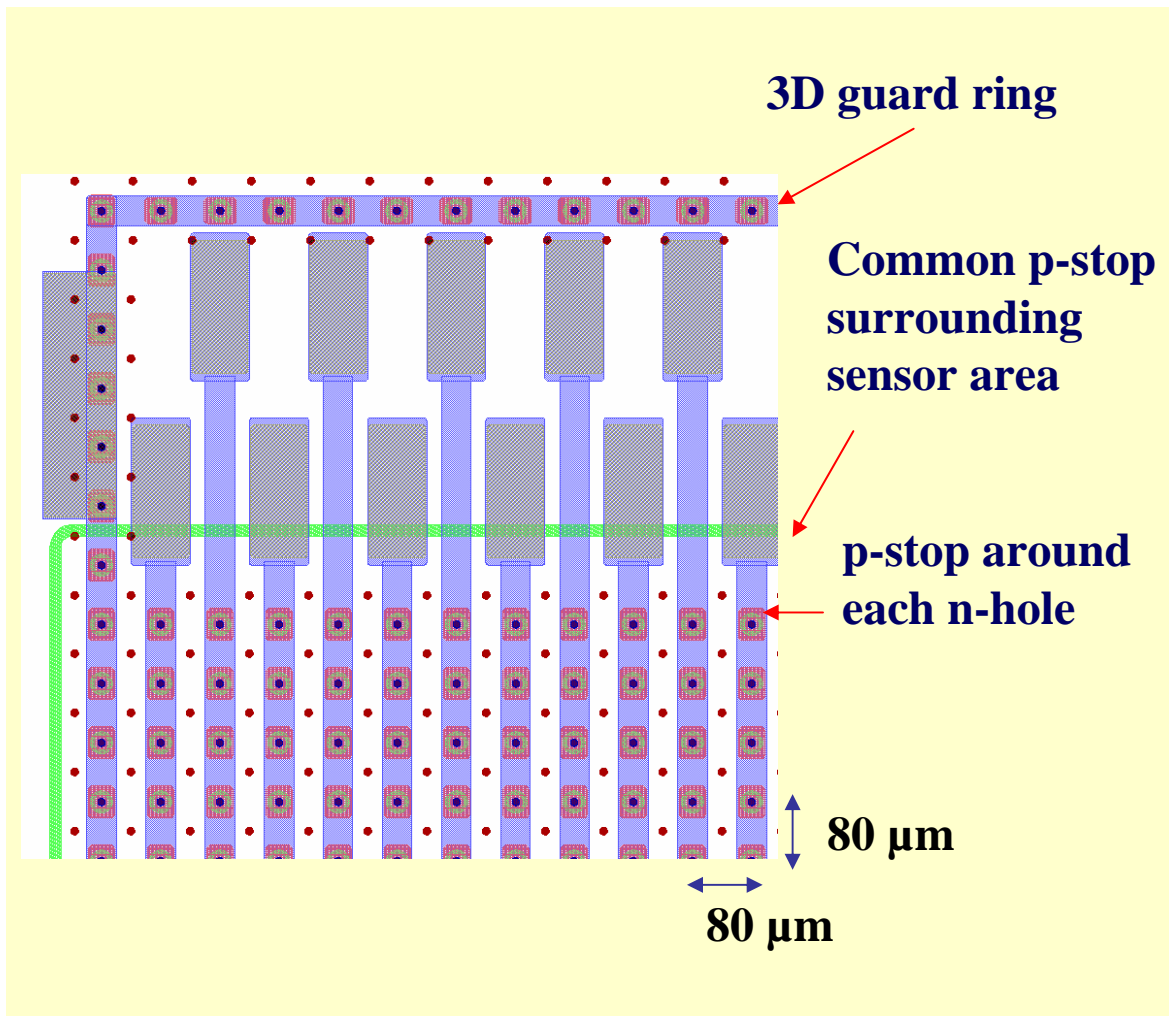
## Electrode fabrication:

1. ICP etching of the holes: Bosch process, ALCATEL 601-E
2. Holes partially filled with 3  $\mu\text{m}$  LPCVD poly
3. Doping with P or B
4. Holes passivated with TEOS  $\text{SiO}_2$

Hole aspect ratio 25:1  
10 $\mu\text{m}$  diameter, 250 $\mu\text{m}$  deep  
P- and N-type substrates, 285 $\mu\text{m}$  thick



# 3D p-type strip detectors



- Devices:
- » n<sup>+</sup> strips
  - » p<sup>-</sup> bulk
  - » p<sup>+</sup> back contact

50 strips  
DC coupled  
50 electrodes/strip  
4mm long strips

Yield for strip detectors in 2008 production = 86%

$$\text{Yield} = \frac{\text{tested good sensors}}{\text{wafers started} \times \text{sensors per wafer}}$$

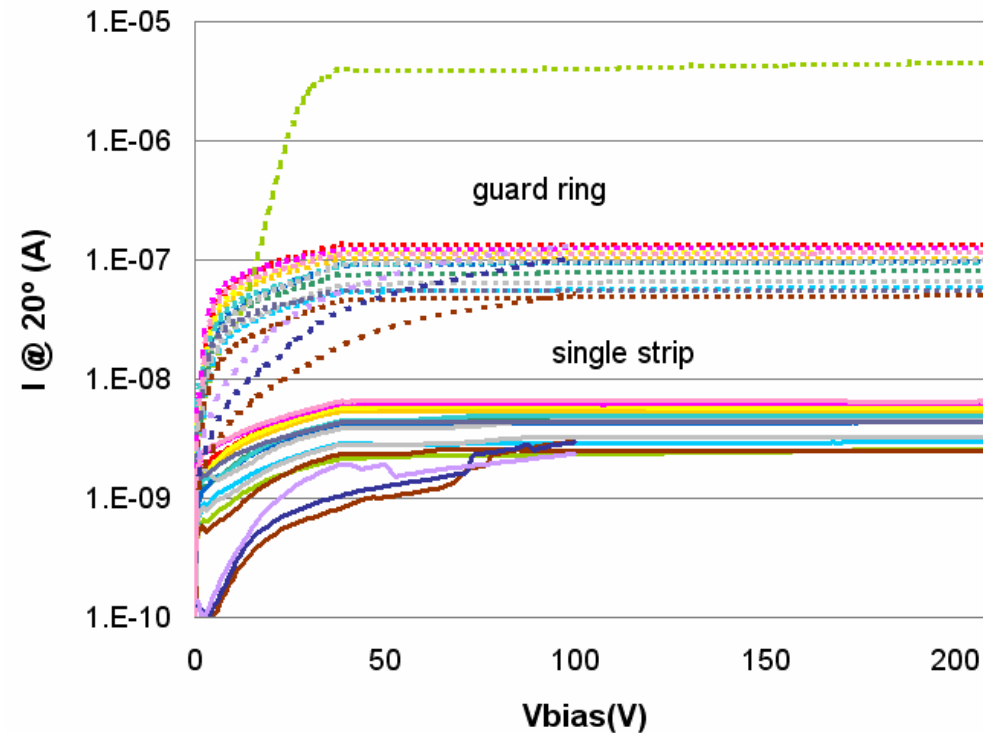
# Leakage current

Before irradiation,  $T = 20^{\circ}\text{C}$

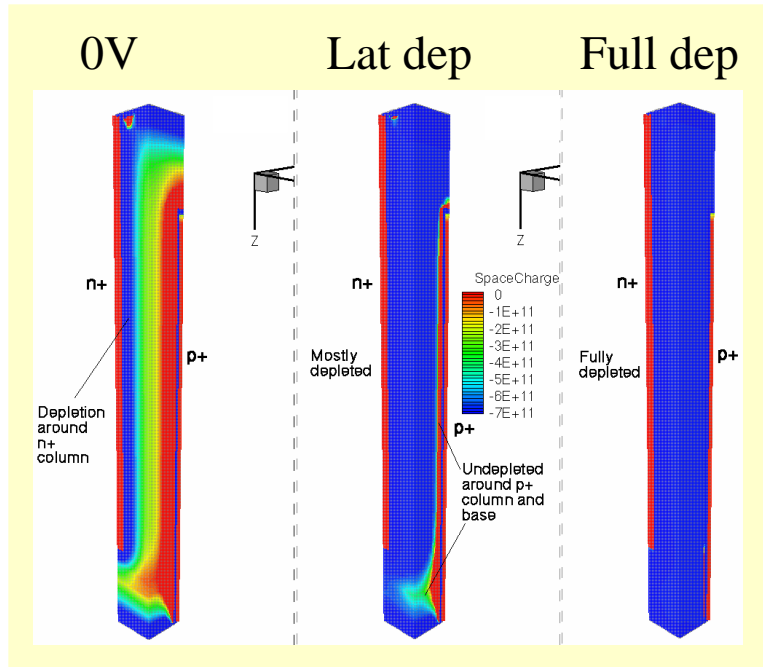
Backside biased, strip and guard ring grounded

- Can see VFD  $\sim 40\text{V}$
- **2 – 6 nA/strip** (40 – 120 pA/column)
- Only 2 detectors, of 19 tested, bad (not shown)
  - Breakdown at less than 5V (catastrophic defect?)
  - All others work far beyond full depletion

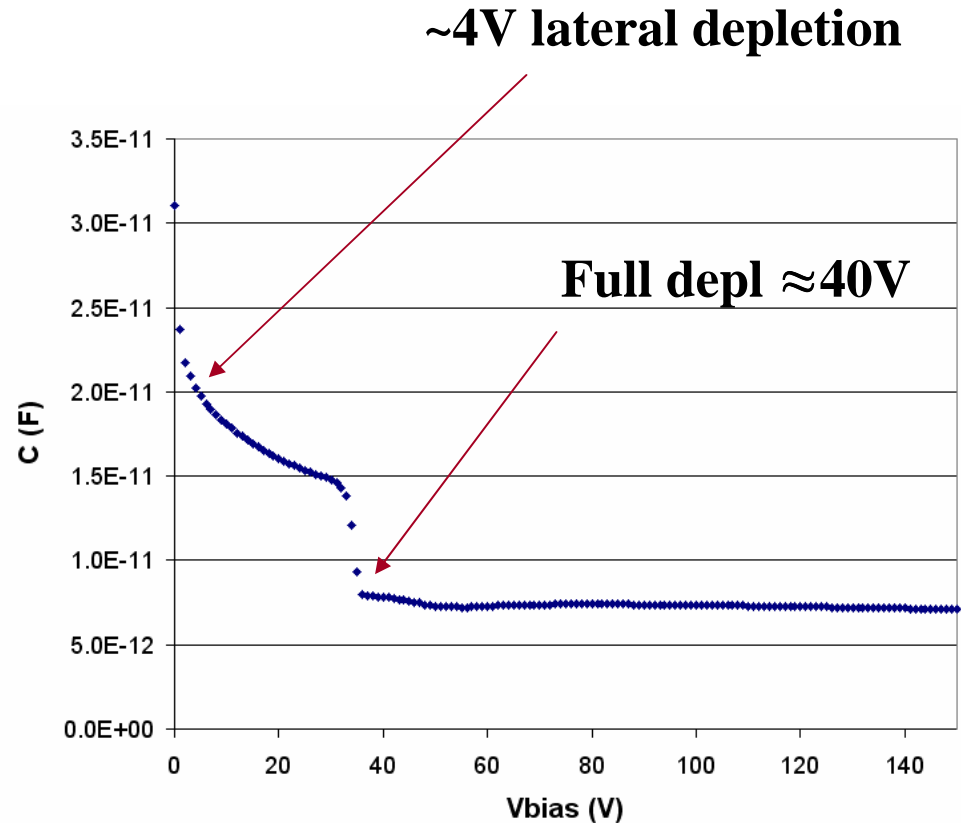
### P-Type DS3D strip detectors



# Bulk capacitance



Simulation by D. Pennicard, Glasgow



Capacitance between strip and backside, neighbours also biased, 20°C, 10 kHz

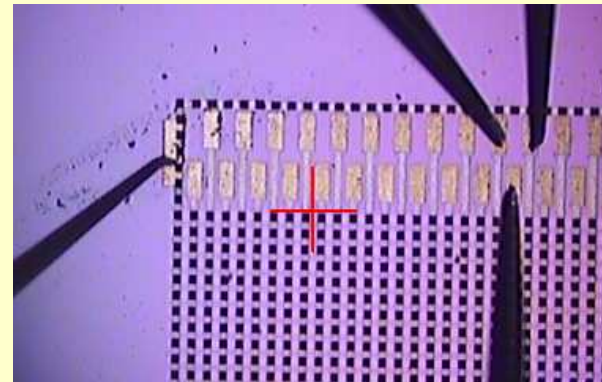
**C = 3 – 7 pF/strip** depending on sensor

# Interstrip resistance

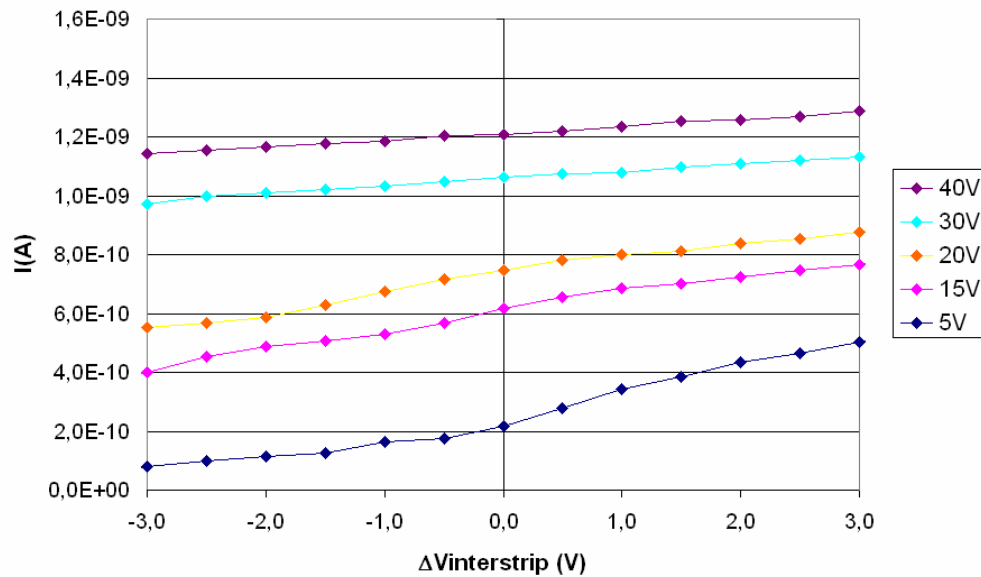
Use two K2410 Sourcemeters:

1. Bias in backside, guard ring to ground
2. Sense test strip, varying voltage, keeping neighbours at ground

$$R_{int} = 2/\text{slope}$$



Non – irradiated I-V interstrip at 20°C



Vbias (V)	Rint (GΩ)
5	28
15	50
20	52
30	99
40	94

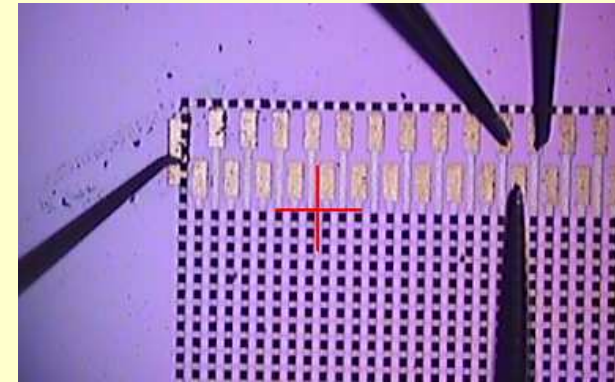
**Good P-stop isolation before irradiation**

# Interstrip capacitance

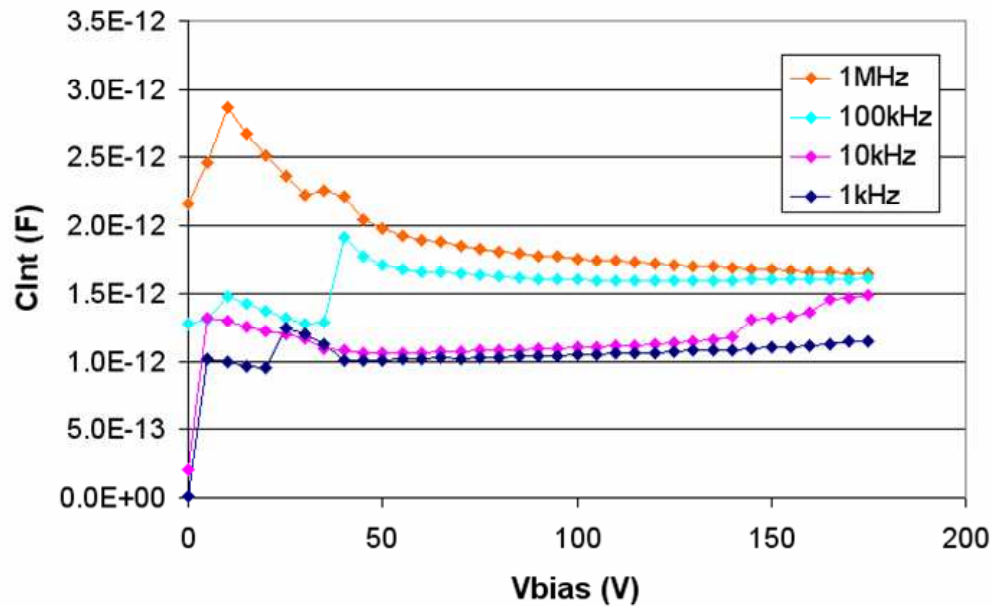
Use K2410 Sourcemeter and HP4284A LCR meter:

- K2410: Bias in backside, guard ring to ground
- 4284A: test strip HIGH, neighbours LOW

3 probes + guard ring



Interstrip Capacitance  
Strip P-type, non-irr, 20°C



- Test  $C_{int}$  as function of frequency
- Values converge for higher frequencies
  - Will use 1 MHz for tests

# Irradiations

(with thanks to Karlsruhe, Freiburg)

- N- and P-bulk short strip detectors were irradiated at Karlsruhe with **26 MeV protons**.
  - Irradiated cold, not biased
- No intentional annealing
  - Max 5 days room temperature
- Distributed to test in Glasgow, Freiburg, CNM.

Fluence (n <sub>eq</sub> /cm <sup>2</sup> )
5E14
1E15
2E15
5E15
1E16
2E16

26 MeV protons scale to 1 MeV neutron equivalent fluence with a hardness factor of 1.85

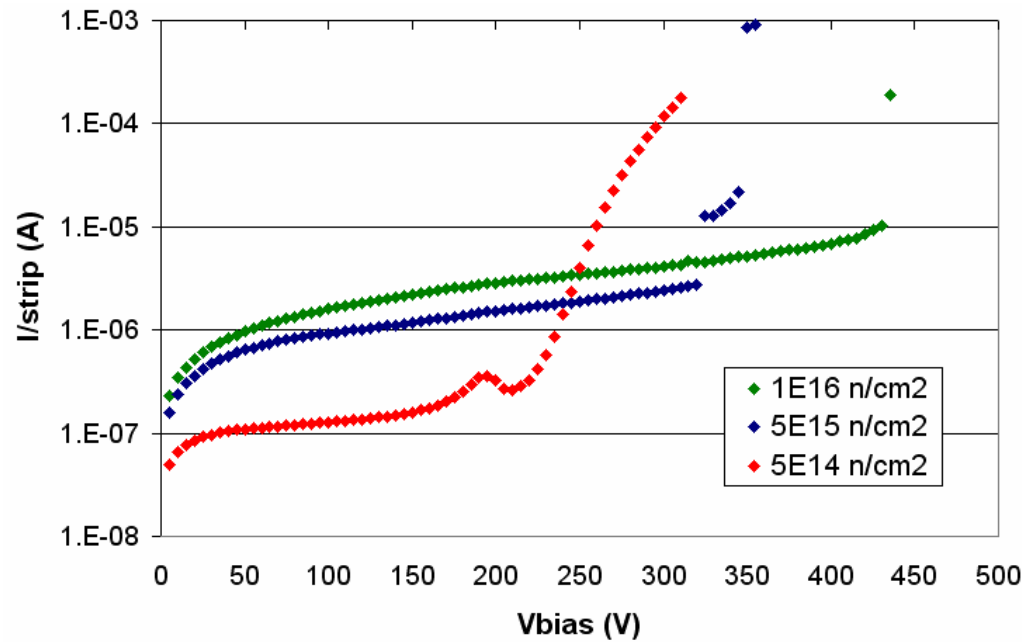
# Annealing

- P-type strip detector irradiated to **10<sup>16</sup> neq/cm<sup>2</sup>**
- Accelerated annealing at **80°C**
  - Acceleration factor of 7400 for the reverse annealing with respect to RT
- All tests at **-10°C** in probe station



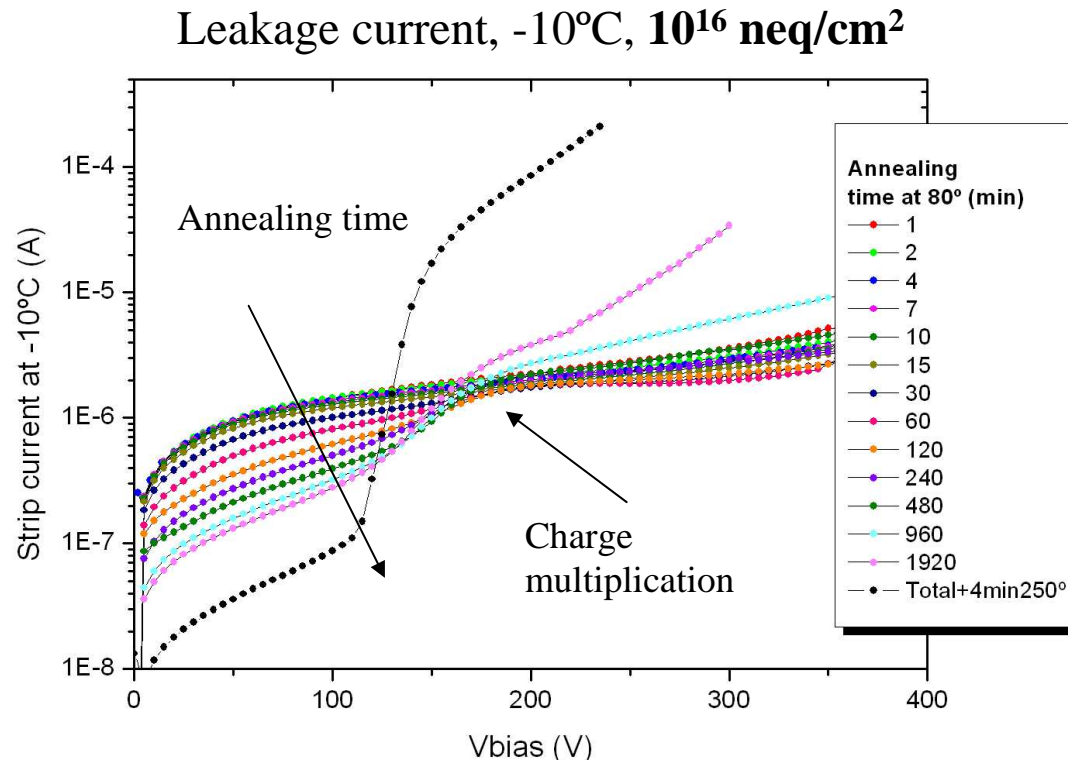
# Leakage current after irradiation

Irradiated p-type, no annealing, -10°C



- Leakage current increases with irradiation dose
- Difficult to estimate damage constant alpha (difficult to calculate Vdep)

# Leakage current vs annealing time

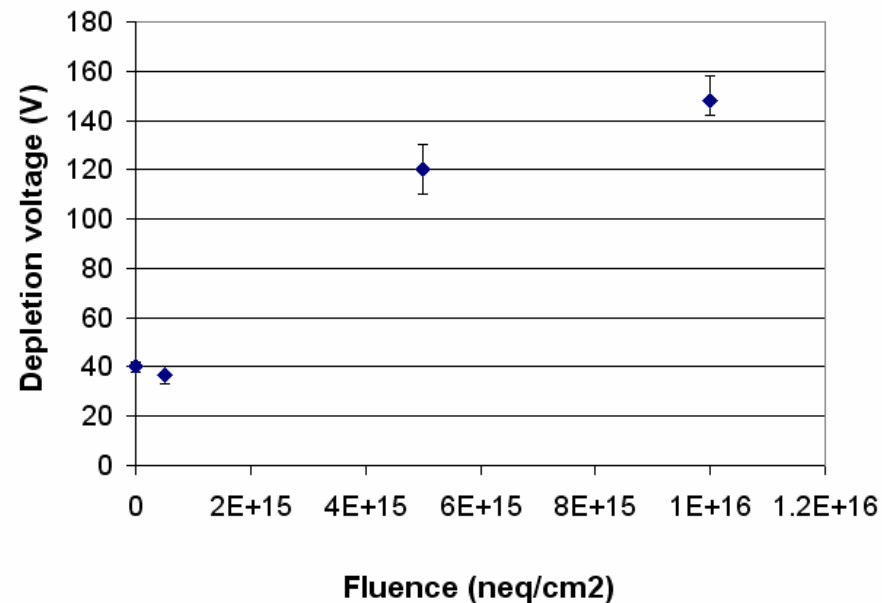
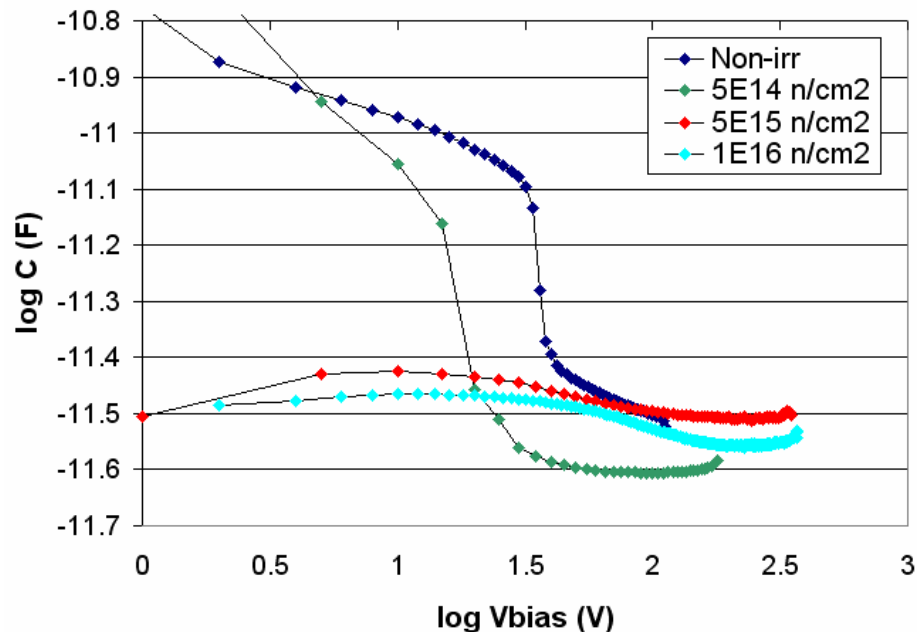


## Two competing effects in annealing curves:

- Annealing of leakage current at low V
- Charge multiplication at  $V \sim 200\text{V}$ . More pronounced and earlier for longer annealing times

# Bulk capacitance vs fluence

Irradiated p-type sensors, no annealing, -10°C

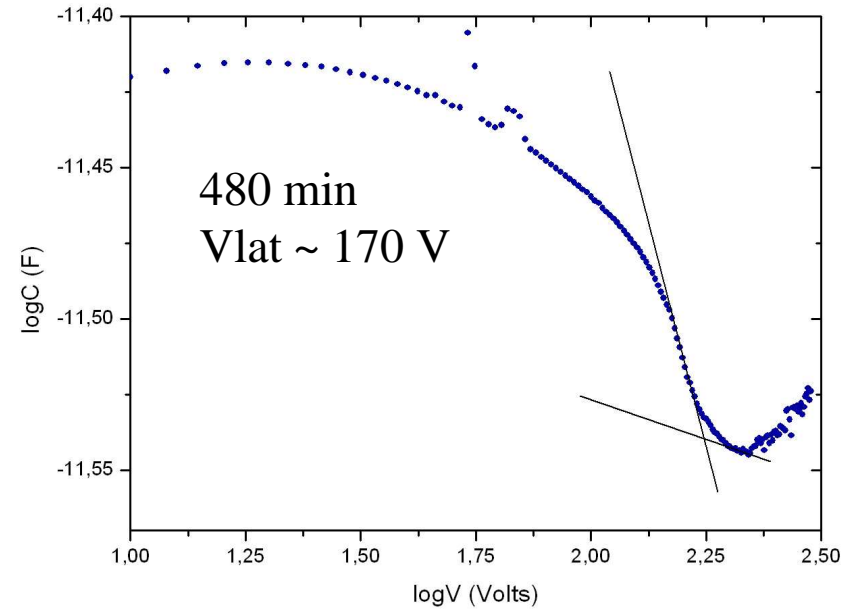
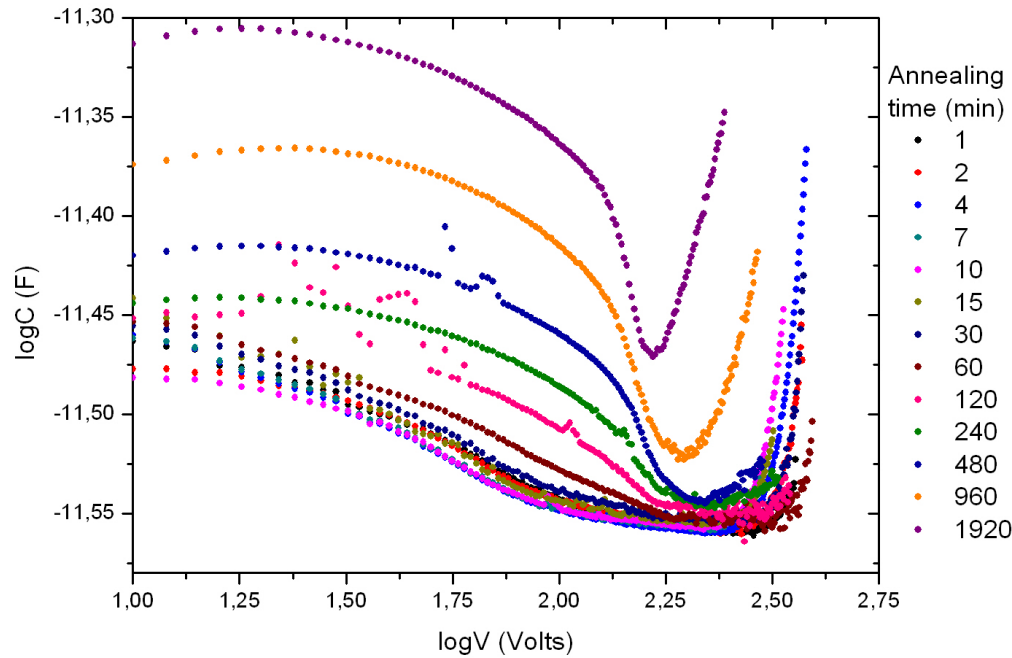


**Lateral depletion voltage estimated from log-log plot, error bars take into account choice of points for lines fitting**

- **Not possible to distinguish full depletion in plots**

# Bulk capacitance vs annealing time

Bulk capacitance,  $-10^{\circ}\text{C}$ , 10 kHz,  $10^{16}$  neq/cm<sup>2</sup>

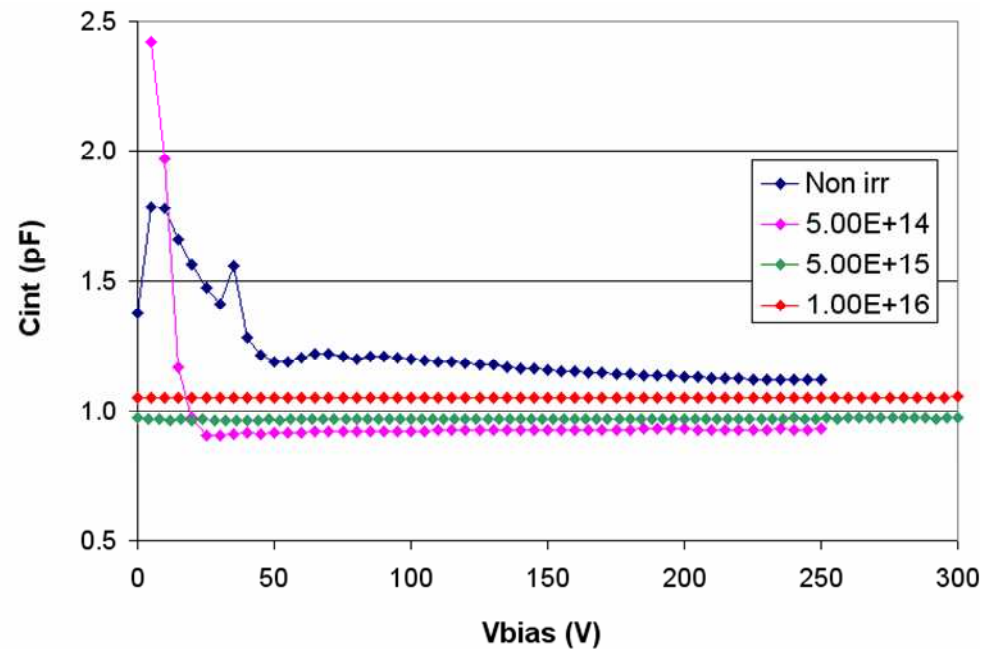


**$V_{lat}$  increases with annealing time at  $80^{\circ}\text{C}$**

**–  $V_{lat}$  (0 min)  $\sim 148$ V,  $V_{lat}$  (480 min)  $\sim 170$ V**

# Interstrip capacitance vs fluence

Irradiated p-type sensors, no annealing, -10°C, 1MHz

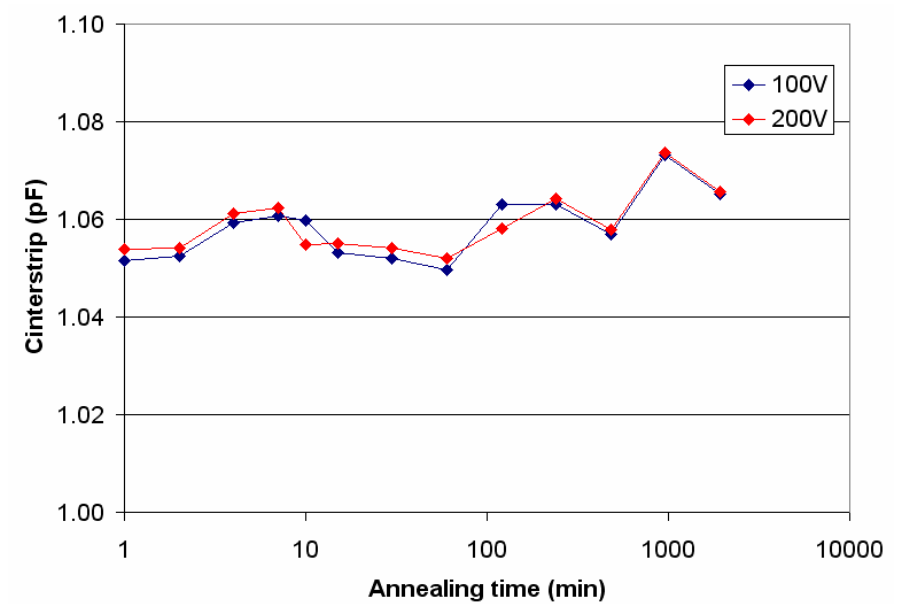
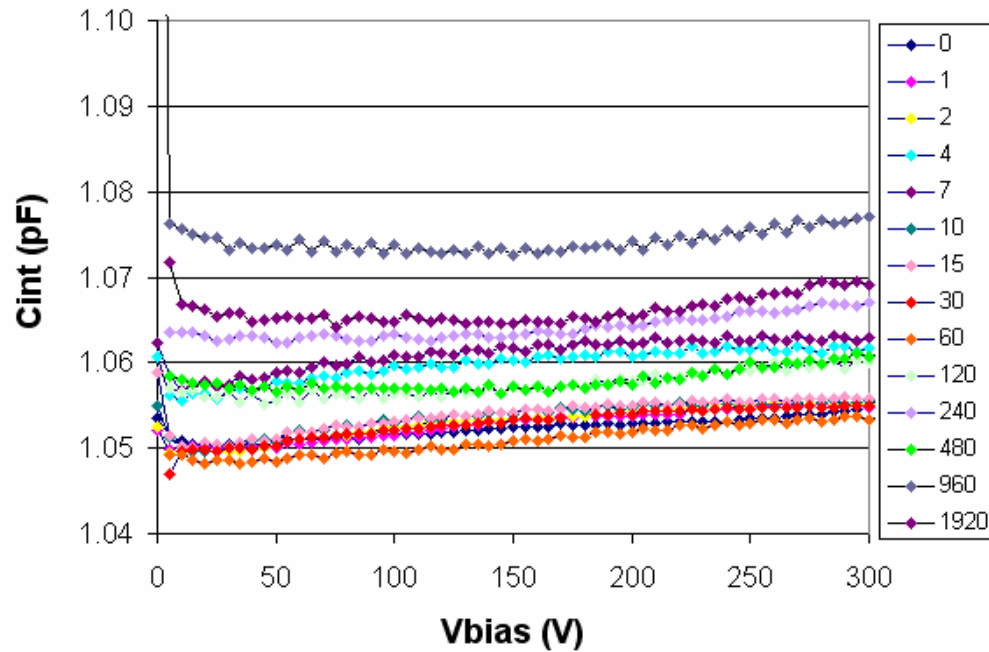


- **Cint saturates at lower voltages for irradiated sensors**
- **Cint seems to decrease with initial irradiation, then increase again with dose.**
  - **Might just be difference between sensors (one for each dose only)**

# Interstrip capacitance vs annealing time



Interstrip capacitance,  $-10^{\circ}\text{C}$ , 1 MHz,  $10^{16}$  neq/cm<sup>2</sup>

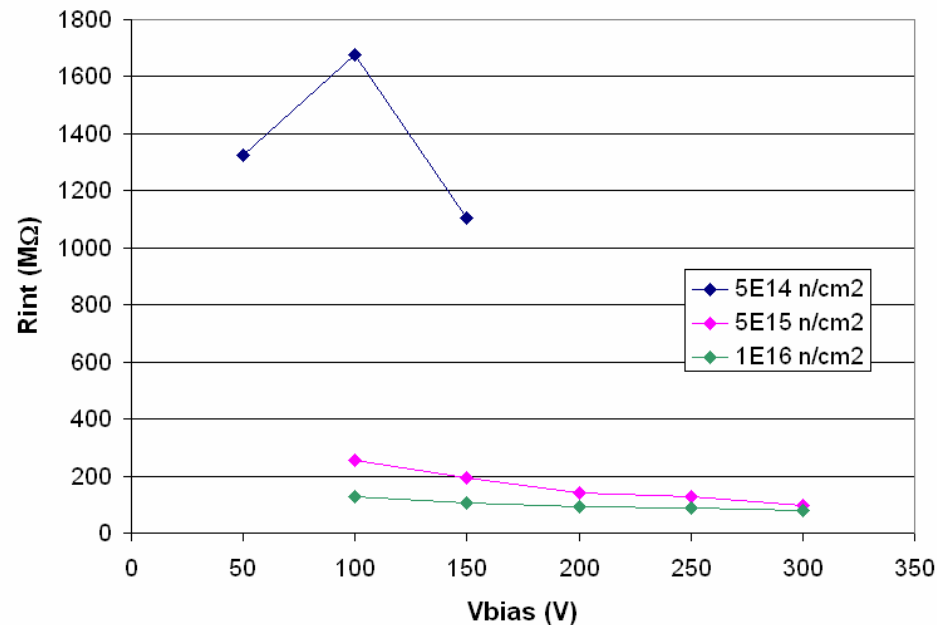


**Interstrip capacitance changes very little with annealing time at  $80^{\circ}\text{C}$ .**

**More likely due to strip to strip variation than annealing effect**

# Interstrip resistance vs fluence

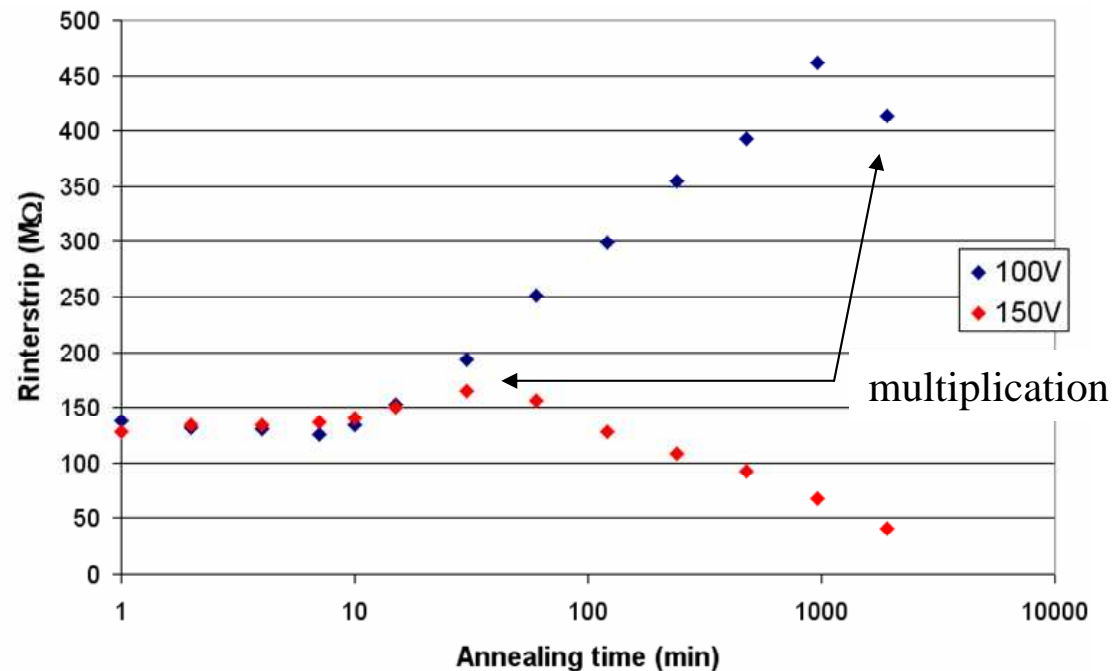
Irradiated p-type sensors, no annealing, -10°C



- Interstrip current too low (pA) to obtain Rint of non-irradiated sensor at -10°C (~100 GΩ at 20°C)
- Measured resistance decreases with irradiation dose as surface isolation decreases
- P-stop works well even for highest irradiation
  - **Rint >100 MΩ for 10<sup>16</sup> neq/cm<sup>2</sup>**

# Interstrip resistance vs annealing time

Interstrip resistance,  $-10^{\circ}\text{C}$ ,  $10^{16}$  neq/cm<sup>2</sup>

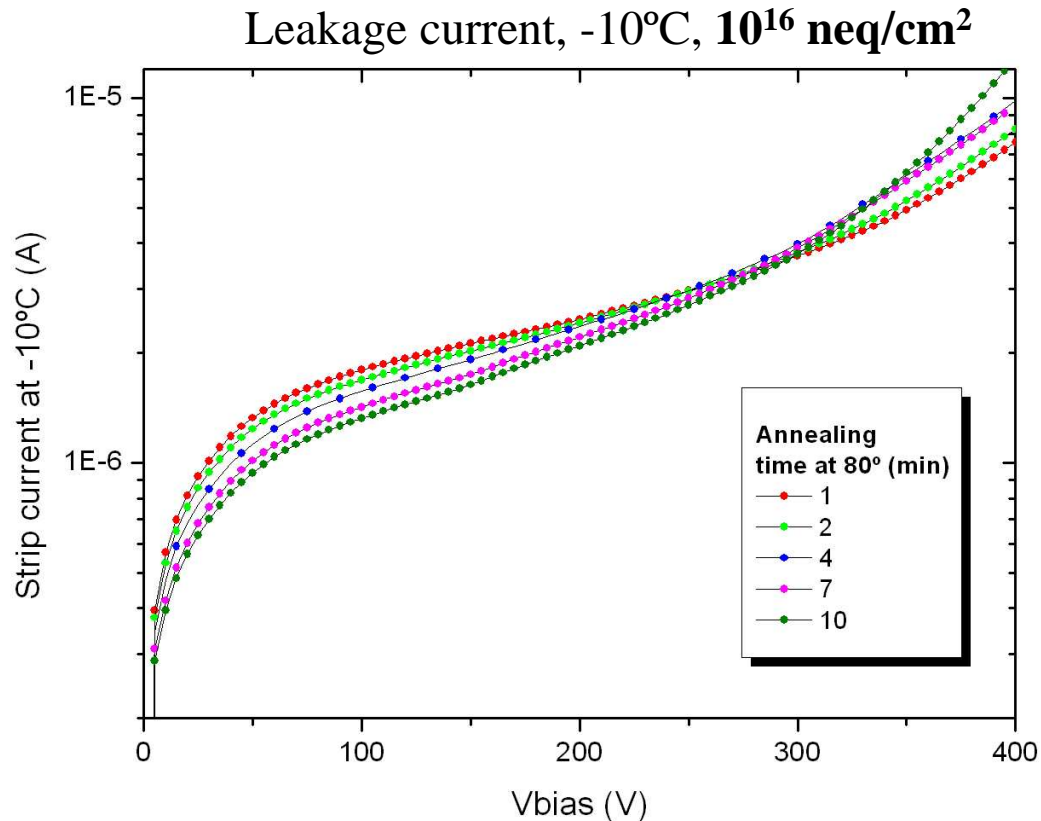


- **100V: interstrip resistance increases with time as substrate becomes more p-type and compensates negative charge in surface**
- **150 V: Rint measured decreases for  $t > 15$  min  $\rightarrow$  charge multiplication**



# N-type detector (preliminary)

- **1E16 neq/cm<sup>2</sup>**
- **Multiplication behaviour similar to p-type sensor**
  - **Starts at higher voltages: ~200V for ptype, ~300V for ntype**

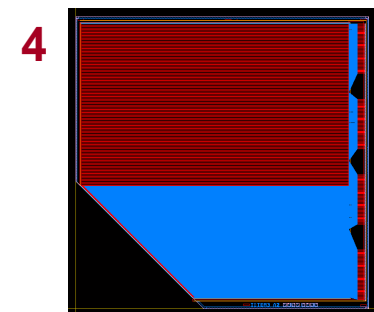
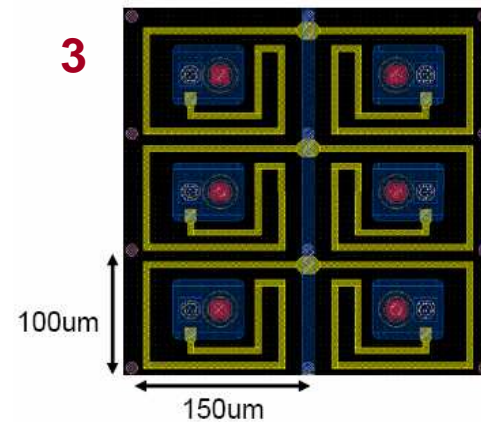
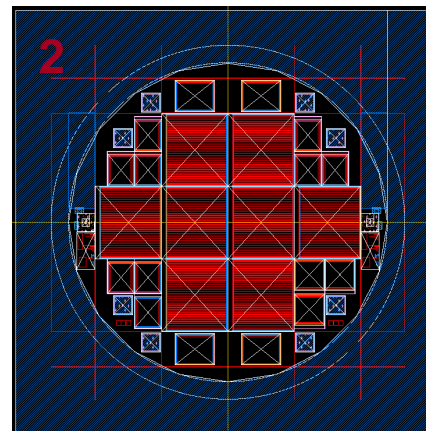
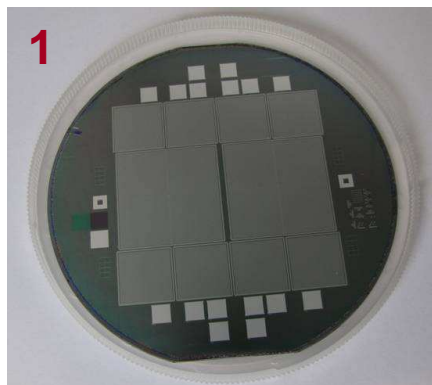


# Conclusions

- I have presented an irradiation and annealing study of 3D P-type strip sensors from CNM irradiated with 26 MeV protons up to  $1E16$  neq/cm<sup>2</sup>
- Depletion voltage increases with irradiation dose and annealing time.  $V(\text{lat depl})$  lower than 150 V for  $1E16$  without annealing
- Leakage current increases with dose, shows typical annealing behaviour for low voltages. Charge multiplication appears at higher voltages, earlier for longer annealing times
- Strip isolation decreases with dose, p-stop works well even for higher irradiation
- Multiplication effect also seen in annealing curves of interstrip resistance
- Interstrip capacitance doesn't change much with irradiation or annealing
- Annealing study of n-type sensor irradiated to  $1E16$  neq/cm<sup>2</sup> started: Multiplication observed but at higher voltages than p-type.

# Future 3D Work

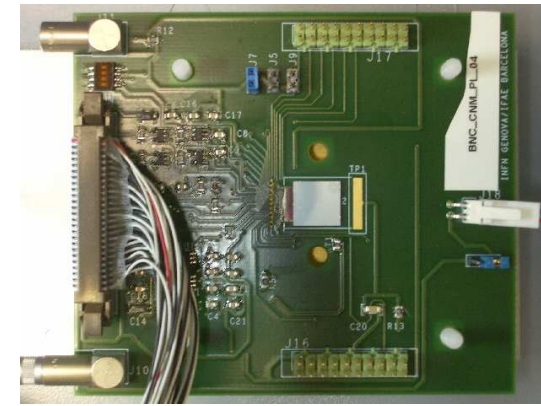
- New run of 3D-Medipix3, standard (2 cm<sup>2</sup>) and quad area (16 cm<sup>2</sup>). Collaboration with Diamond Light Source and Glasgow Uni (1)
- Irradiation and test beams with Medipix (Timepix) detectors for LHCb VELO upgrade.
- ATLAS pixels FE-I3 and new FE-I4 fabrication, irradiation and test beam. For the IBL, in the framework of the ATLAS 3D Collaboration (<http://test-3dsensor.web.cern.ch/test-3dsensor/>). (2)
- Design and fabrication of CMS pixels: single chips and 8x2 module. In collaboration with PSI. (3)
- Design and fabrication of 3D strip detectors for TOTEM (CERN) (4)



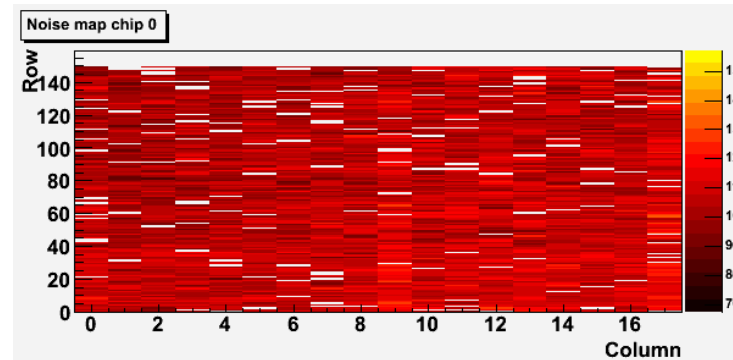
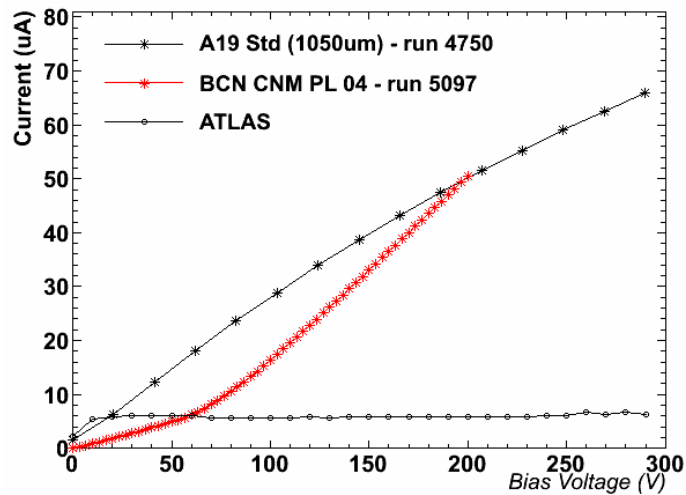
# Other Activities



- Full production/testing chain at Barcelona
  - Sensor production
  - Sensor/Front-end chip integration (bumpbonding to wirebonding)
  - Device characterization



## I. Leakage Current (FE-I3)



II. Noise Map:  
most pixels  
working

## III. Ionization test ( $Am^{241}$ )

